08/26/10

Anaren Integrated Radio – Recommended reflow profile

The AIR Radio Module recommended solder reflow profile is based on IPC/JEDEC J-STD-020.

Table 5-2 Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (Tsmax to Tp)	3° C/second max.	3° C/second max.
Preheat - Temperature Min (Ts_{min}) - Temperature Max (Ts_{max}) - Time (Ts_{min} to Ts_{max}) (ts)	100 °C 150 °C 60-120 seconds	150 °C 200 °C 60-180 seconds
Time maintained above: - Temperature (T_L) - Time (t_L)	183 °C 60-150 seconds	217 °C 60-150 seconds
Peak Temperature (Tp)	See Table 4.1	See Table 4.2
Time within 5°C of actual Peak Temperature (tp)[2]	10-30 seconds	20-40 seconds
Ramp-down Rate	6 °C/second max.	6 °C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package body surface.
Note 2: Time within 5 °C of actual peak temperature (tp) specified for the reflow profiles is a "supplier" minimum and "user" maximum.

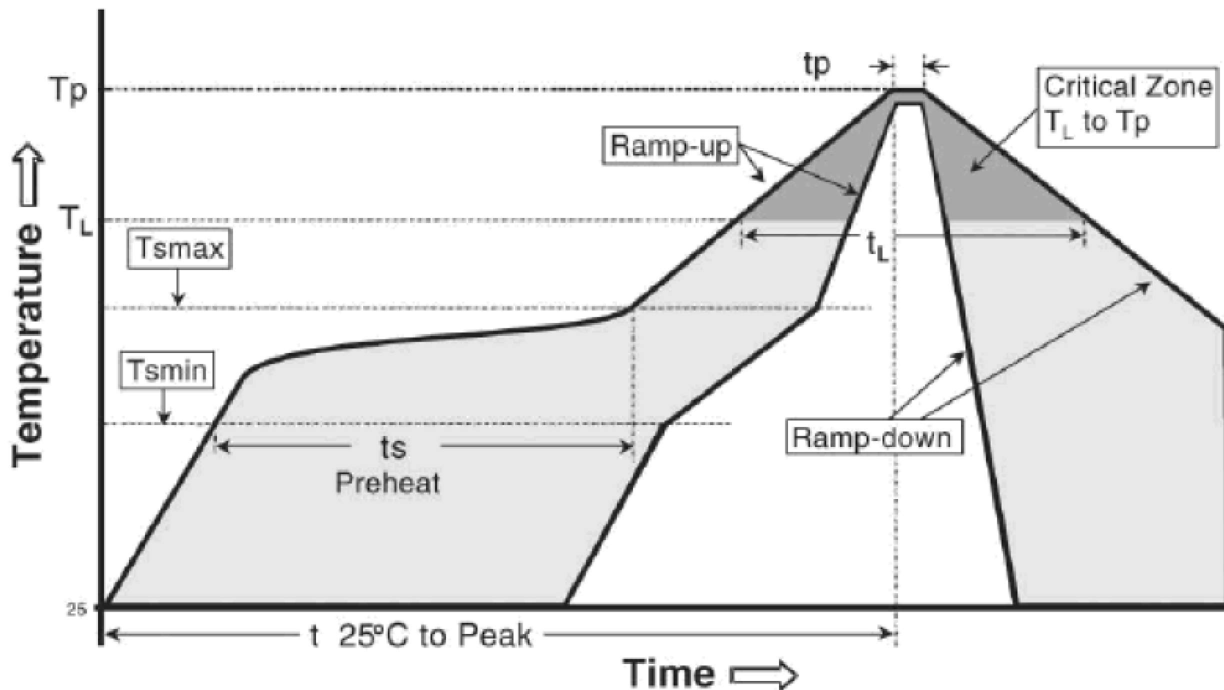

Figure 5-1 Classification Reflow Profile

Table 4-1 SnPb Eutectic Process - Package Peak Reflow Temperatures

Package Thickness	Volume mm^3 <350	Volume mm^3 ≥ 350
<2.5 mm	240 +0/-5 °C	225 +0/-5°C
≥ 2.5 mm	225 +0/-5°C	225 +0/-5°C

Table 4-2 Pb-free Process - Package Peak Reflow Temperatures

Package Thickness	Volume mm^3 < 350	Volume mm^3 350 - 2000	Volume mm^3 > 2000
< 1.6 mm	260 °C *	260 °C *	260 °C *
1.6 mm - 2.5 mm	260 °C *	250 °C *	245 °C *
> 2.5 mm	250 °C *	245 °C *	245 °C *

* Tolerance: The device manufacturer/supplier shall assure process compatibility up to and including the stated classification temperature at the rated MSL level